# 12 V, 4.0 A, Low V<sub>CE(sat)</sub> PNP Transistor

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are miniature surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable\*
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

, , , ,				
Rating	Symbol	Max	Unit	
Collector-Emitter Voltage	V <sub>CEO</sub>	-12	Vdc	
Collector-Base Voltage	V <sub>CBO</sub>	-12	Vdc	
Emitter-Base Voltage	V <sub>EBO</sub>	-7.0	Vdc	
Collector Current - Continuous	I <sub>C</sub>	-2.0	Α	
Collector Current - Peak	I <sub>CM</sub>	-4.0	Α	
Electrostatic Discharge	ESD	HBM Class 3B MM Class C		

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 1)	460 3.7	mW mW/°C
Derate above 25°C		3.7	IIIVV/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	270	°C/W
Total Device Dissipation T <sub>A</sub> = 25°C	P <sub>D</sub> (Note 2)	540	mW
Derate above 25°C		4.3	mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	230	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 3)	710	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

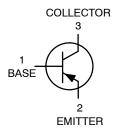
- 1. FR-4 @ 100 mm<sup>2</sup>, 1 oz. copper traces.
- 2. FR-4 @ 500 mm<sup>2</sup>, 1 oz. copper traces.
- 3. Thermal response.



#### ON Semiconductor®

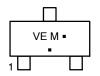
www.onsemi.com

# $^{-12}$ VOLTS $$4.0~{\rm AMPS}$$ PNP LOW ${\rm V_{CE(sat)}}$ TRANSISTOR EQUIVALENT ${\rm R_{DS(on)}}$ 65 m $\Omega$





#### MARKING DIAGRAM



VE = Specific Device Code

M = Date Code\*

■ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS12200LT1G, NSV12200LT1G*	SOT-23 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•		-
Collector – Emitter Breakdown Voltage ( $I_C = -10$ mAdc, $I_B = 0$ )	V <sub>(BR)</sub> CEO	-12	-	-	Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-12	-	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	-7.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -12 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	-	-0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -7.0 Vdc)	I <sub>EBO</sub>	-	-	-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 4) $ (I_C = -10 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -2.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $	h <sub>FE</sub>	250 250 200 150	- 300 - -	- - - -	
Collector – Emitter Saturation Voltage (Note 4) $ \begin{aligned} &(I_C = -0.1 \text{ A, } I_B = -0.010 \text{ A}) \text{ (Note 5)} \\ &(I_C = -1.0 \text{ A, } I_B = -0.100 \text{ A}) \\ &(I_C = -1.0 \text{ A, } I_B = -0.010 \text{ A}) \\ &(I_C = -2.0 \text{ A, } I_B = -0.200 \text{ A}) \end{aligned} $	V <sub>CE(sat)</sub>	- - - -	-0.008 -0.065 -0.100 -0.130	-0.011 -0.090 -0.120 -0.180	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = -1.0 \text{ A}, I_B = -0.01 \text{ A})$	V <sub>BE(sat)</sub>	_	-	-0.900	V
Base – Emitter Turn–on Voltage (Note 4) (I <sub>C</sub> = -1.0 A, V <sub>CE</sub> = -2.0 V)	V <sub>BE(on)</sub>	-	-	-0.900	V
Cutoff Frequency ( $I_C = -100 \text{ mA}$ , $V_{CE} = -5.0 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>	100	-	-	MHz
Input Capacitance (V <sub>EB</sub> = -0.5 V, f = 1.0 MHz)	Cibo	-	-	350	pF
Output Capacitance (V <sub>CB</sub> = -3.0 V, f = 1.0 MHz)	Cobo	-	-	120	pF
SWITCHING CHARACTERISTICS					
Delay ( $V_{CC} = -10 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>d</sub>	-	-	60	ns
Rise ( $V_{CC} = -10 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>r</sub>	-	-	120	ns
Storage ( $V_{CC} = -10 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>s</sub>	-	-	250	ns
Fall ( $V_{CC} = -10 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>f</sub>	_	-	130	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

5. Guaranteed by design but not tested.

#### **TYPICAL CHARACTERISTICS**

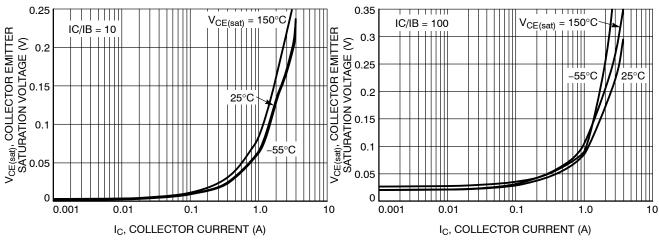


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. Collector Emitter Saturation Voltage vs. Collector Current

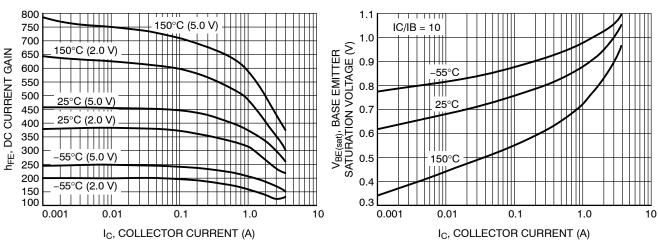


Figure 3. DC Current Gain vs. Collector Current

Figure 4. Base Emitter Saturation Voltage vs.
Collector Current

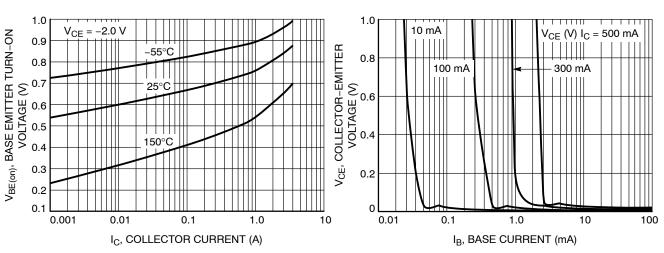
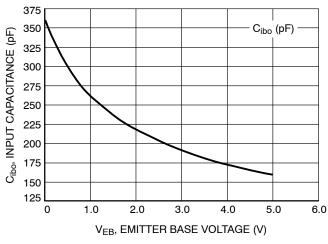


Figure 5. Base Emitter Turn-On Voltage vs. Collector Current

Figure 6. Saturation Region

#### **TYPICAL CHARACTERISTICS**



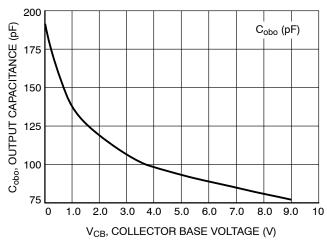


Figure 7. Input Capacitance

Figure 8. Output Capacitance

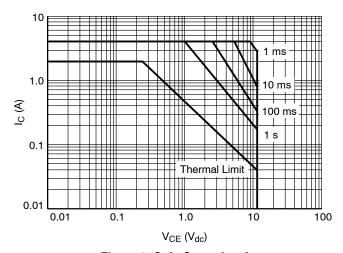


Figure 9. Safe Operating Area



SOT-23 (TO-236) CASE 318-08 **ISSUE AS** 

**DATE 30 JAN 2018** 

# SCALE 4:1 D - 3X b

**TOP VIEW** 







#### **RECOMMENDED SOLDERING FOOTPRINT**



DIMENSIONS: MILLIMETERS

#### NOTES:

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
  MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,

	PROT	RUSIONS, OR GATE BURRS.	
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	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

#### **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code

= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE
OT (1 F O			

SOT-23 (TO-236)

STYLE 9:	STYLE 10:	STYLE 11:	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN	PIN 1. ANODE	PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
<ol><li>ANODE</li></ol>	<ol><li>SOURCE</li></ol>	<ol><li>CATHODE</li></ol>	<ol><li>CATHODE</li></ol>	2. DRAIN	2. GATE
<ol><li>CATHODE</li></ol>	3. GATE	<ol><li>CATHODE-ANODE</li></ol>	<ol><li>ANODE</li></ol>	3. GATE	<ol><li>ANODE</li></ol>

STYLE 15:	STYLE 16:	STYLE 17:	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE	PIN 1. NO CONNECTION	PIN 1. NO CONNECTION	PIN 1. CATHODE	PIN 1. CATHODE
<ol><li>CATHODE</li></ol>	<ol><li>CATHODE</li></ol>	2. ANODE	<ol><li>CATHODE</li></ol>	2. ANODE	<ol><li>ANODE</li></ol>
<ol><li>ANODE</li></ol>	<ol><li>CATHODE</li></ol>	<ol><li>CATHODE</li></ol>	<ol><li>ANODE</li></ol>	<ol><li>CATHODE-ANOD</li></ol>	E 3. GATE

STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
<ol><li>SOURCE</li></ol>	<ol><li>OUTPUT</li></ol>	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3 DRAIN	3 INPLIT	3 CATHODE	3. SOURCE	3. GATE	<ol><li>NO CONNECTION</li></ol>

STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE	
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